

Drill Map:

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- 0.50mm / 0.020" (8 holes)

- 0.60mm / 0.024" (6 holes)

- 0.80mm / 0.031" (80 holes)

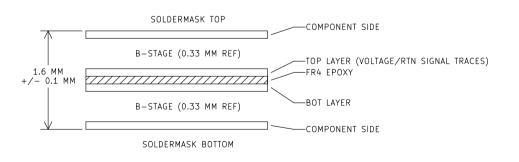
- 0.90mm / 0.035" (6 holes)

- 1.00mm / 0.039" (4 holes + 3 slots)

- 1.10mm / 0.043" (13 holes)

* 3.50mm / 0.138" (4 holes) (not plated)
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LAYER DETAIL



GENERAL NOTES

- FABRICATE PER ANSI/IPC-1-600, IPC-QE-605, IPC-4101, IPC-4552 AND IPC-SM-840 SPECIFICATIONS. MUST USE ROHS-COMPLIANT MATERIALS.
- MATERIAL: BASE MATERIAL LAMINATED EPOXY GLASS FR-4, NOM .062", COLOUR NATURAL. NOM 1 OZ COPER WEIGHT. THICKNESS .070" MAX AFTER PLATING AND FINISHING. PREFER ROHS COMPLIANT PER IPC-4101 SLASH SHEETS #26 OR #83 OR #98 WITH MINIMUM TG 135 DEGREE C OR HIGHER, TD 300 DEGREE C OR HIGHER AND FLAME RATED UL 94V-0.
- SOLDERMASK BOTH SIDES OF BOARD OVER BARE COPPER WITH MATERIAL PER ANSI/IPC-SM-840, COLOR SHALL BE GREEN.
- APPLY SOLDER PLATING WITH HOT-AIR LEVELLING TO EXPOSE COPPER BOTH SIDES. LEAD-FREE SOLDER REQUIRED.
- INDICATED AREA ON BOTTOM SIDE AVAILABLE FOR APPLICATION OF PCB MANUFACTURER LOGO, UL MARKING, AND DATE-CODE. USE OF OTHER LOCATION TO BE APPROVED BY PURCHASER.
- 6. APPLY SILKSCREEN TO TOP SIDE OF BOARD USING NON-CONDUCTIVE WHITE EPOXY INK.
- 7. SEE FABRICATION FILES WITH SAME TITLE OR DRAWING NUMBER, AND REVISION, AS THIS DRAWING.
- 8. DIMNESONAL TOLERANCES ARE: .XX=+/- .25 MM; .XXX=+/-.127 MM.
- 9. OUTLINE DEFINED IN SEPARATE GERBER FILE. DIMENSIONS OF CIRCUMSCRIBED RECTANGLE SHOWN ON THIS DWG FOR REF ONLY.
- 10. SEE SEPERATE DRILL FILE FOR HOLE LOCATIONS. SELECTED HOLE LOCATIONS SHOWN ON THIS DWG FOR REF ONLY.
- 11. HOLE LOCATIONS SPECIFIED IN SEPERATE DRILL FILE TAKE PRECEDENCE OVER THIS DWG AND ARTWORK. CONTACT PURCHASER TO RESOLVE DIMENSION CONFLICT BETWEEN DWG AND ARTWORK.
- 12. HOLE SIZES ARE SPECIFIED AS FINAL DIMENSIONS AFTER PLATING AND FINISHING. UNLESS OTHERWISE SPECIFIED ALL HOLES TO BE PLATED.
- 13. VENDOR TO PLATE HOLES AND EXPOSED PADS. VENDOR TO SPECIFY TYPE OF PLATING MATERIAL TO BE USED WHEN ACCEPTING ORDER.
- 14. AFTER ASSEMBLY TRIM SOLDER FILLETS AND COMPONENT LEADS TO 1.5 MM (MAX) BEYOND BOARD SURFACE ON BOTTOM SIDE.
- 15. DESIGN GEOMETRY MINIMUM FEATURE SIZES:

TRACE WIDTH; ANULUS	0.50 MM	TRACE-TO-TRACE; TRACE-TO-PAD	0.20 MM
HOLE-TO-HOLE	1.50 MM	PAD-TO-PAD	0.20 MM
SILKSCREEN LINE	0.20 MM	SILKSCREEN-TO-BARE COPPER	0.20 MM
MINIMUM HOLE SIZE (PLATED)	0.60 MM	MAXIMUM HOLE SIZE (UNPLATED)	3.50 MM
BOARD EDGE-TO-COPPER ´	0.50 MM	,	

Drawn by: Andrew Li

Sheet:

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